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TABLE OF CONTENTS

Laser Treatment of Organic Thin Film Solar Cells	1
Fe-42%Ni Austenitic Alloy as a Novel Substrate for Flexible Electronics	5
Concepts of Metal-Organic Decomposition (MOD) Silver Inks for Structured Metallization by Inkjet Printing	3
Roll-to-roll Manufacture of Pentacene-based Thin Film Transistors with a Flash-evaporated Polymer Dielectric Cured with an E-beam	9
Mass-printed Integrated Circuits with Enhanced Performance Using Novel Materials and Concepts 2: Georg C. Schmidt, Maxi Bellmann, Heiko Kempa, Mike Hambsch, Kay Reuter, 2: Michael Stanel, Arved C. Hübler 2:	5

Author Index